

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**PATENT**

In re application of: Mostafazadeh et al.

Attorney Docket No.: NSC1P225R

Patent No.: 6,117,710

Issued: September 12, 2000

Title: PLASTIC PACKAGE WITH EXPOSED  
DIE AND METHOD OF MAKING SAME

Box Reissue  
Commissioner for Patents  
Washington, DC 20231

**REISSUE APPLICATION DECLARATION BY INVENTORS**

As a below-named inventor, I hereby declare that:

1. My residence and citizenship are stated below next to my name.
2. I have reviewed and understand the contents of the specification and claims of the above-identified reissue application, and believe myself to be an original, first, and joint inventor of the invention described and claimed in the above-identified reissue application and in U.S. Letters Patent No. 6,117,710 on which the reissue application is based.
3. I do not know and do not believe that said invention was ever known or used in the United States of America before the invention thereof by myself.
4. I acknowledge a duty to disclose information I am aware of which is material to patentability as defined in 37 C.F.R. § 1.56.

5. I believe that the original patent, U.S. Patent No. 6,117,710, is partly inoperative since the patent claims may potentially be interpreted by some as covering less than I had the right to claim in the patent. As an example, claim 1 of the '710 patent requires that the leads extend "radially from a central opening." However, I believe that the invention is equally applicable regardless of the orientation of the leads.

6. All errors being corrected in this reissue arose without any deceptive intent on my part.

I declare further that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

Date: 10/31/01

Shahram Mostafazadeh  
Shahram Mostafazadeh

4238 Monet Circle

San Jose, CA 95136  
Residence Address

United States of America  
Citizenship and Country of Residence

Date: 10/31/01

Joseph O. Smith  
Joseph O. Smith

16915 John Telfer Drive

Morgan Hill, CA 95037  
Residence Address

United States of America  
Citizenship and Country of Residence

---

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

---

In re application of: Mostafazadeh et al.

Attorney Docket No.: NSC1P225R

Original Patent No.: 6,117,710

Original Patent Issue Date: September 12, 2000

Title: PLASTIC PACKAGE WITH EXPOSED  
DIE AND METHOD OF MAKING SAME

---

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail to: Commissioner for Patents, Washington, DC 20231 on January 11, 2002

Signed: Lara M. Nelson

Lara M. Nelson

**POWER OF ATTORNEY BY ASSIGNEE AND 37 CFR §3.73 STATEMENT**

Commissioner for Patents  
Washington, D. C. 20231

Sir:

**National Semiconductor Corporation** is the assignee of the above-referenced patent application by virtue of an assignment document. The assignment document is/was recorded:

- ☒ at Reel 8415, Frame(s) 0221
- ☒ on February 11, 1997
- ☐ submitted concurrently herewith

The assignee represents, pursuant to 37 C.F.R. §3.73(b), that the undersigned is a representative authorized and empowered to sign on behalf of the assignee.

Pursuant to 37 C.F.R. §§1.36 and 3.71, the assignee hereby revokes all powers of attorney previously given and hereby appoints the law firm of Beyer Weaver & Thomas, LLP and all practitioners who are associated with the **Customer Number 022434** as principal attorneys to prosecute this application and transact all business in the Patent and Trademark Office connected therewith.

Please send all correspondence for this application as follows:

**Customer Number 022434**  
BEYER WEAVER & THOMAS, LLP  
P.O. Box 778  
Berkeley, CA 94704-0778



Please direct any calls to **Steve D Beyer** (650) 961-8300.

Assignee of Interest:

National Semiconductor Corporation  
2900 Semiconductor Drive  
Santa Clara, CA 95051

Date 12/11/01 *CD*  
November 20, 2001

*CRB*  
\_\_\_\_\_  
Name: Christopher J. Byrne  
Title: Director of Intellectual Property and  
Technology Licensing

2004-15-01-10

**PATENT**

---

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

---

In re application of: Mostafazadeh et al.

Attorney Docket No.: NSC1P225R

Original Patent No.: 6,117,710

Original Patent Issue Date: September 12, 2000

For: PLASTIC PACKAGE WITH EXPOSED DIE  
AND METHOD OF MAKING SAME

---

**Establishing Right Of Assignee To Take Action  
and Consent Of Assignee  
under 37 C.F.R. 1.172(a) and 3.73(b)**Commissioner of Patents and Trademarks  
Washington, D.C. 20231

Sir:

The assignee of the entire right, title and interest hereby seeks to take action in the Patent and Trademark Office in this matter.

**IDENTIFICATION OF ASSIGNEE**

The assignee of the entire right, title and interest of the above-identified application/patent is held by National Semiconductor Corporation.

**BASIS OF ASSIGNEE'S INTEREST**

Ownership by the assignee is established by assignment document recorded at reel, 8415 frame 0221. A copy of the assignment is attached hereto.

**DECLARATIONS**

I, the undersigned, have reviewed all of the evidentiary documents for the above-identified application, and, to the best of my knowledge and belief, title is in the assignee seeking to take this action.

I hereby declare that all statements made herein of my own knowledge are true, and that all statements made on information and belief are believed to be true; and further, that these statements are made with the knowledge that willful false statements, and the like so made, are

NSC1P225R

-1-

2011-01-07 10:44:00

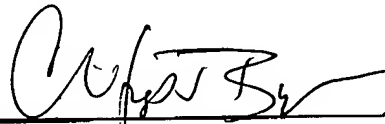
punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

#### ASSENT OF ASSIGNEE

National Semiconductor Corporation, owner of U.S. Patent No. 6,117,710 by virtue of the assignment document referenced above, hereby assents to the filing of an application for reissue of said patent and to the issuance of a reissue patent therefor.

Date:

1/9/02



Christopher J. Byrne  
Director of Intellectual Property and Technology  
Licensing  
National Semiconductor Corporation

2007-01-23 14:00

ASSIGNMENT

For good and valuable consideration, receipt of which is hereby acknowledged, we

Shahram Mostafazadeh

of

Santa Clara, CaliforniaJoseph O. Smith

of

Morgan Hill, California

hereby sell, assign and transfer to National Semiconductor Corporation, a Delaware corporation, having a place of business at 2900 Semiconductor Drive, Santa Clara, California, 95052-8090, its successors and assigns, the entire right, title and interest throughout the world in our invention in

"PLASTIC PACKAGE WITH EXPOSED DIE AND METHOD OF MAKING SAME"

for which we have filed a United States Patent Application on or about this date, and all patent applications and patents of every country for said invention, including divisions, reissues, continuations and extensions thereof, and all rights of priority resulting from the filing of said applications; we authorize the above-named assignee to apply for patents of foreign countries for said invention, and to claim all rights of priority without further authorization from us; we agree to execute all papers useful in connection with said United States and foreign applications, and generally to do everything possible to aid said assignee, their successors, assigns and nominees, at their request and expense, in obtaining and enforcing patents for said invention in all countries; and we request the Commissioner of Patents and Trademarks to issue all patents granted for said invention to the above-named assignee, its successors and assigns.

Executed this 11th day of Feb, 1997.

Shahram Mostafazadeh  
(Shahram Mostafazadeh)

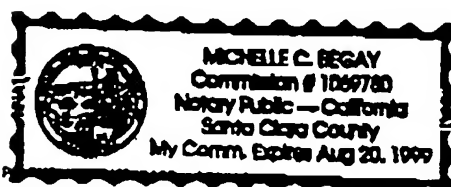
State of California )

County of Santa Clara ) ss.

on 2/11/97 before me, Michelle C. Regay personally appeared Shahram Mostafazadeh personally known to me or proved to me on the basis of satisfactory evidence to be the person whose name is subscribed to the within instrument and acknowledged to me that he executed the same in his authorized capacity, and that by his signature on the instrument the person, or the entity upon behalf of which the person acted, executed the instrument.

WITNESS my hand and official seal.

Michelle C. Regay  
SIGNATURE OF NOTARY

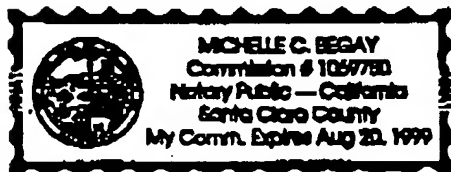


Executed this 11 day of February, 1997.

Joseph O. Smith  
(Joseph O. Smith)

State of California )  
County of Santa Clara ) ss.

On 2/11/97 before me, Michelle C. Begay  
personally appeared Joseph O. Smith personally known to me or proved to me on  
the basis of satisfactory evidence to be the person whose name is subscribed  
to the within instrument and acknowledged to me that he executed the same in  
his authorized capacity, and that by his signature on the instrument the  
person, or the entity upon behalf of which the person acted, executed the  
instrument.



WITNESS my hand and official seal.

Michelle C. Begay  
SIGNATURE OF NOTARY

10044132-01102